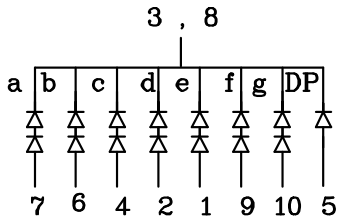
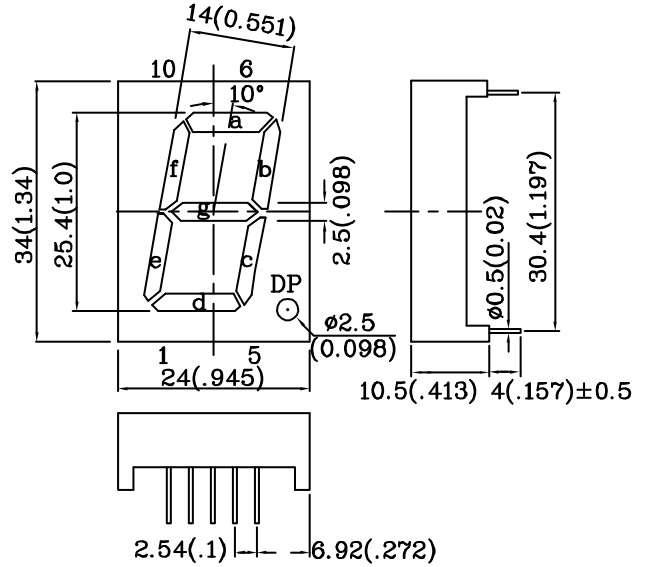


**Features**

- 1.0 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- HIGH LIGHT OUTPUT.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- STANDARD : GRAY FACE, WHITE SEGMENT.
- RoHS COMPLIANT.



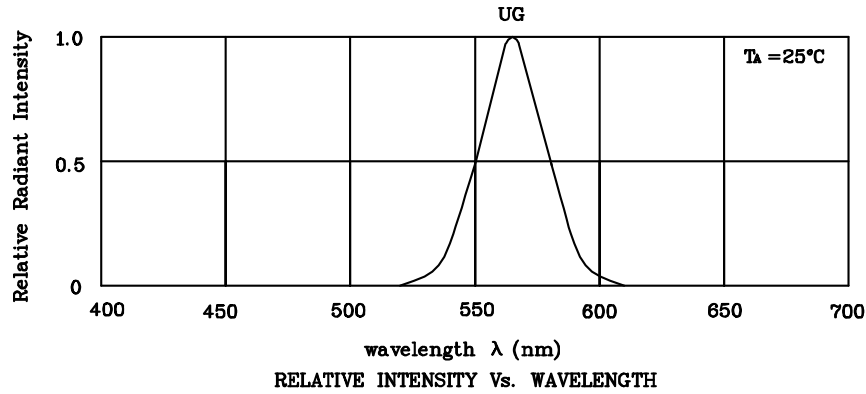
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$ " unless otherwise noted.

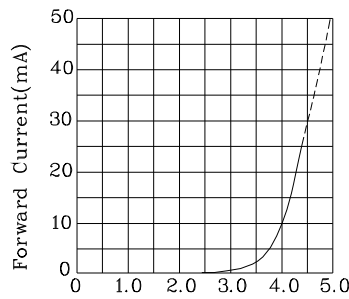
Absolute Maximum Ratings (TA=25°C)	UG (GaP)	Unit
Reverse Voltage Per Segment or (Dp)	VR	10(5) V
Forward Current Per Segment or (Dp)	IF	25(25) mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width Per Segment or (Dp)	iFS	140(140) mA
Power Dissipation Per Segment or (Dp)	PT	125(62.5) mW
Operating Temperature	TA	-40 ~ +85 °C
Storage Temperature	Tstg	-40 ~ +85 °C
Lead Solder Temperature [2mm Below Package Base]	260°C For 5 Seconds	

Operating Characteristics (TA=25°C)	UG (GaP)	Unit
Forward Voltage (Typ.) (IF=10mA) Per Segment or (Dp)	VF	4.0(2.0) V
Forward Voltage (Max.) (IF=10mA) Per Segment or (Dp)	VF	5.0(2.5) V
Reverse Current (VR=10V(5V)) Per Segment or (Dp)	IR	10 (10) uA
Wavelength of Peak Emission (IF=10mA)	$\lambda P$	565 nm
Wavelength of Dominant Emission (IF=10mA)	$\lambda D$	568 nm
Spectral Line Full Width At Half-Maximum (IF=10mA)	$\Delta\lambda$	30 nm
Capacitance (VF=0V, f=1MHz)	C	15 pF

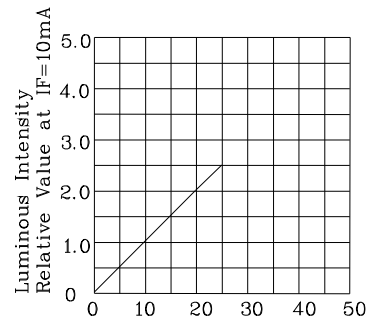
Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd		Wavelength nm $\lambda$ P	Description
			min.	typ.		
XDUG25C	Green	GaP	4700	23990	565	Common Cathode, Rt. Hand Decimal



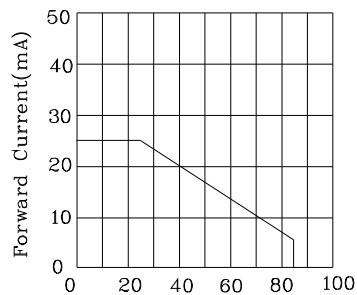
❖ UG



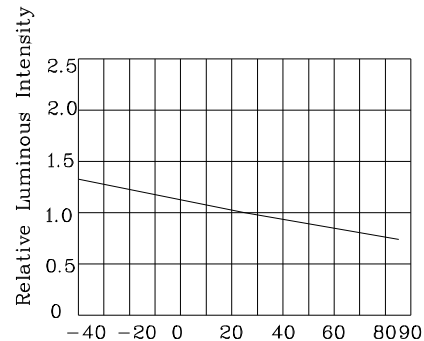
Forward Voltage(V)  
FORWARD CURRENT Vs  
FORWARD VOLTAGE



IF-Forward Current (mA)  
LUMINOUS INTENSITY Vs.  
FORWARD CURRENT

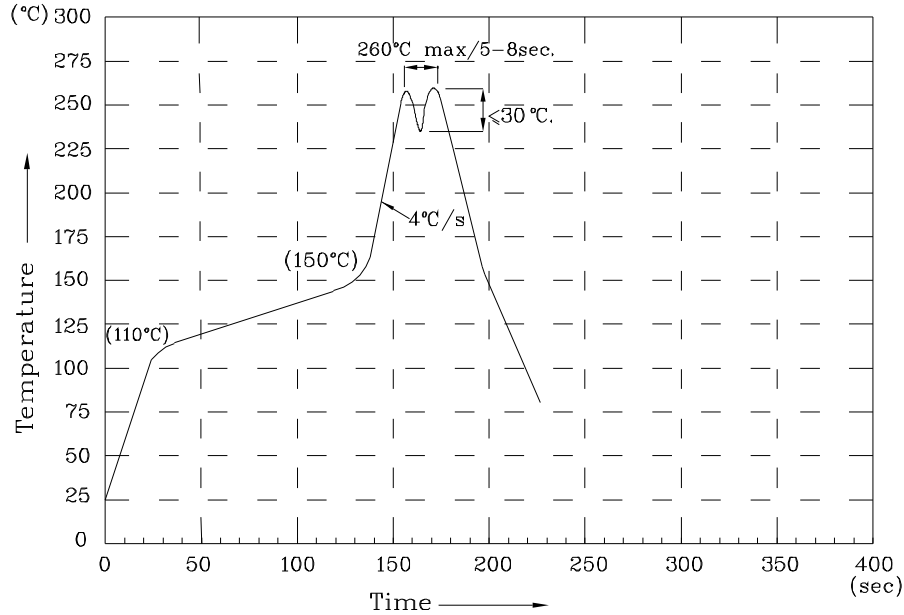


Ambient Temperature  $T_A$  (°C)  
FORWARD CURRENT  
DERATING CURVE



Ambient Temperature  $T_A$  (°C)  
LUMINOUS INTENSITY Vs.  
AMBIENT TEMPERATURE

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.